

**Specifications** 

Insulation Resistance



ESD SMD Comm COG, Ceramic, 0.01 uF, 1%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805, 0.6 mm



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

0805
2mm +/-0.3mm
1.25mm +/-0.3mm
0.9mm +/-0.10mm
0.6mm MIN
0.5mm +/-0.25mm

	Capacitance	0.01 uF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	1%
	Voltage DC	100 VDC
	ESD Level per AEC-Q200	25,000 V ESD Level
	Dielectric Withstanding Voltage	250 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications		
Packaging	Bulk, Bag	
Packaging Quantity	1	

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